

APM1402SC-TRL-VB Datasheet

N-Channel 20 V (D-S) MOSFET

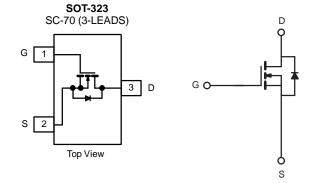
PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)		
	0.036 at V _{GS} = 10 V	4			
20	0.040 at V _{GS} = 4.5 V	3.8	4 nC		
	0.048 at V _{GS} = 2.5 V	3.6			





COMPLIANT HALOGEN FREE

- 100 % R_a Tested
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

- Portable Devices
 - Load Switch
 - Battery Switch
- · Load Switch for Motors, Relays and Solenoids

ABSOLUTE MAXIMUM RATING	S (T _A = 25 °C, unl	ess otherwis	e noted)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V_{GS}	± 12	V	
	T _C = 25 °C		4 ^a		
Continuous Proin Current (T = 150 °C)	T _C = 70 °C	l _D	3.6 ^a		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C		4 ^{a, b, c}		
	T _A = 70 °C	1	3.7 ^{b, c}	А	
Pulsed Drain Current (t = 300 µs)		I _{DM}	20		
Continuous Source-Drain Diode Current	T _C = 25 °C		2.3 ^a		
Continuous Source-Drain Diode Current	T _A = 25 °C	· I _S	1.3 ^{b, c}		
	T _C = 25 °C		2.8		
Maximum Power Discipation	T _C = 70 °C] _{D.}	1.8	W	
Maximum Power Dissipation	T _A = 25 °C	P _D	1.56 ^{b, c}	VV	
	T _A = 70 °C		1.0 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	60	80	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	34	45	C/VV		

Notes:

- a. Package limited, $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 125 °C/W.



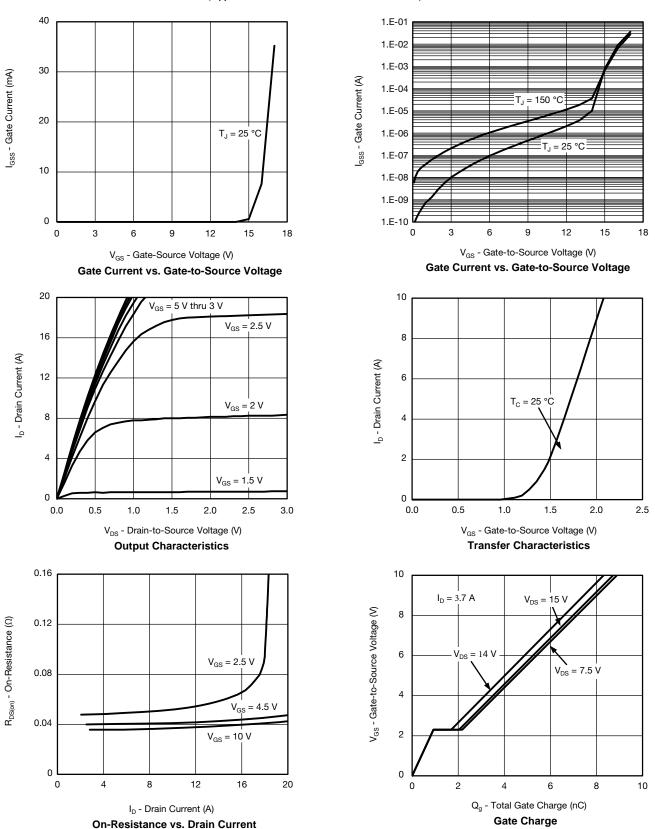
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	1 2						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			23		1406	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	I _D = 250 μA		- 3.2		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	0.6		1.3	V	
Octo Octobra Lankson		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 0.5		
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 12 V			± 25	μA	
Zara Oata Walkana Basin Oamant	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 55 °C			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	15			Α	
	, ,	V _{GS} = 10 V, I _D = 3.7 A		0.036			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 3.6 A		0.040		Ω	
		V _{GS} = 2.5 V, I _D = 1.5 A		0.048			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 3.7 A		17		S	
Dynamic ^b	•						
Total Octo Observe		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.7 \text{ A}$		8.8	13.5		
Total Gate Charge	Q_g			4	6	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 3.7 \text{ A}$		0.9			
Gate-Drain Charge	Q _{gd}			1.1			
Gate Resistance	R _g	f = 1 MHz	0.4	2	4	kΩ	
Turn-On Delay Time	t _{d(on)}			0.29	0.58		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 4.1 \Omega$		0.4	0.8]	
Turn-Off DelayTime	t _{d(off)}	$I_D \approx 3.7 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		1.9	3.8		
Fall Time	t _f			0.75	1.5	1	
Turn-On Delay Time	t _{d(on)}			0.1	0.2	μs	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 4.1 \Omega$		0.15	0.3		
Turn-Off DelayTime	t _{d(off)}	$I_D \approx 3.7 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		3	6		
Fall Time	t _f			0.75	1.5		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.3		
Pulse Diode Forward Current	I _{SM}				20	A	
Body Diode Voltage	V _{SD}	I _S = 3.7 A, V _{GS} = 0 V		0.85	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			12	25	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 07 0 11/11 100 0/ 7 07 00		5	10	nC	
Reverse Recovery Fall Time	t _a	$I_F = 3.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		6.5			
Reverse Recovery Rise Time	t _b	\dashv		5.5		ns	

Notes:

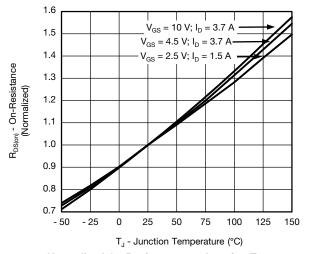
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

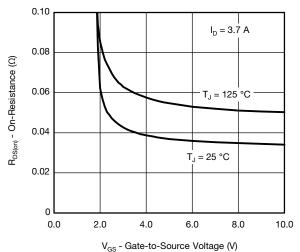




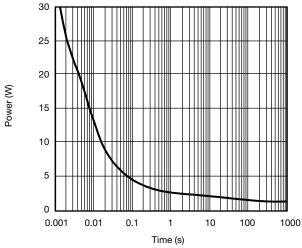




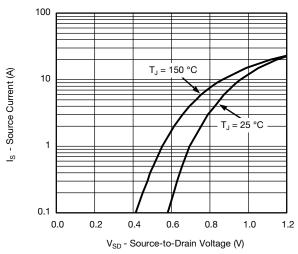
Normalized On-Resistance vs. Junction Temperature



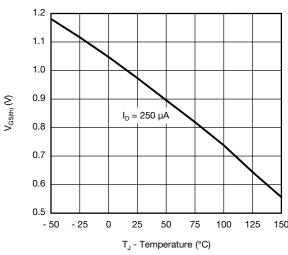
On-Resistance vs. Gate-to-Source Voltage



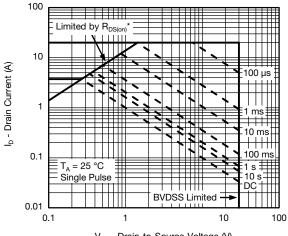
Single Pulse Power, Junction-to-Ambient



Source-Drain Diode Forward Voltage

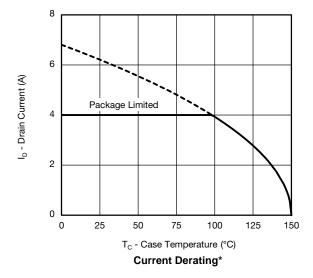


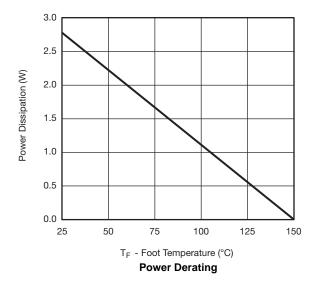
Threshold Voltage



$$\begin{split} &V_{DS}\text{ - Drain-to-Source Voltage (V)}\\ ^*V_{GS}>&\min\text{mum }V_{GS}\text{ at which }R_{DS(on)}\text{ is specified}\\ \textbf{Safe Operating Area, Junction-to-Ambient} \end{split}$$

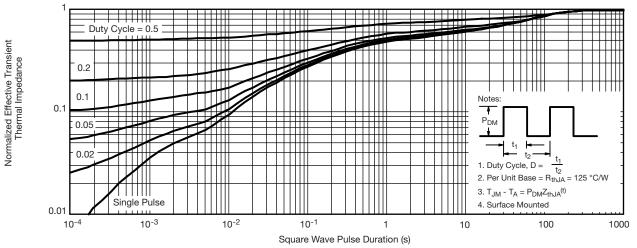




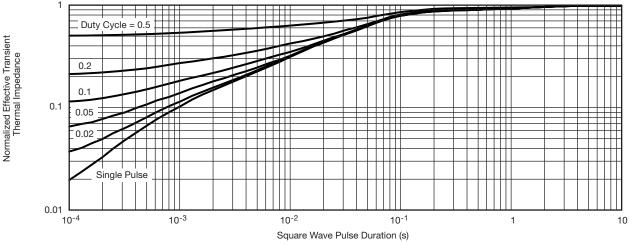


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





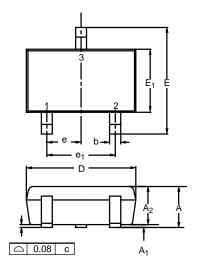
Normalized Thermal Transient Impedance, Junction-to-Ambient

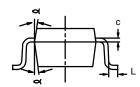


Normalized Thermal Transient Impedance, Junction-to-Foot



SC-70: 3-LEADS



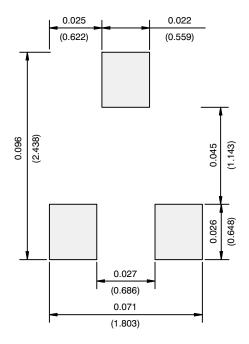


90 - 80 25 10	2.00	Max 1.10 0.10 1.00 0.40 0.25	Min 0.035 - 0.031 0.010 0.004	Nom	Max 0.043 0.004 0.039 0.016
- 80 25 10	- - - -	0.10 1.00 0.40 0.25	- 0.031 0.010	- - - -	0.004 0.039 0.016
25 10	- - -	1.00 0.40 0.25	0.010	- - -	0.039
25 10		0.40 0.25	0.010	- - -	0.016
10	- -	0.25		-	
-	-		0.004	_	0.010
80 2	2.00				
	2.00	2.20	0.071	0.079	0.087
80 2	2.10	2.40	0.071	0.083	0.094
15 ′	1.25	1.35	0.045	0.049	0.053
e 0.65BSC				0.026BSC	;
20 ′	1.30	1.40	0.047	0.051	0.055
10 (0.20	0.30	0.004	0.008	0.012
7°	Nom		7°Nom		
	20 10 (20 1.30	20 1.30 1.40 10 0.20 0.30	20 1.30 1.40 0.047 10 0.20 0.30 0.004	20 1.30 1.40 0.047 0.051 10 0.20 0.30 0.004 0.008

DWG: 5549



RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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